
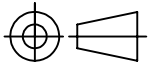


REVISION HISTORY				
ECN	REV	DESCRIPTION	DATE	APPROVAL

- NOTES UNLESS OTHERWISE SPECIFIED.
1. MATERIAL:
A. SUBSTRATE: ROGERS RT6202, 0.020 THICK
B. MET1 AND MET2: 1 OZ. COPPER PER LAYER
C. SOLDERMASK: BLACK TAIYO PSR-4000, TOP SIDE ONLY WHERE INDICATED
D. SILKSCREEN: WHITE
2. UNLESS SPECIFIED OTHERWISE, TOLERANCES ARE:
A. PCB OUTLINE AND CUTOUT $\pm .003$
3. BURRS SHALL NOT EXCEED .002.
4. COPPER IS PULLED BACK .002 ON MET1 AND MET2 FROM EDGE OF PCB.
5. MET1 (TOP METAL) FEATURES TO BE WITHIN 0.002 OF CAD DATABASE.
6. ALL VIAS TO BE LOCATED WITHIN $\pm .002$ OF CAD DATABASE.
7. FABRICATE IN ACCORDANCE WITH IPC-6012 CLASS2.
8. INSPECT TO IPC-600 CLASS 2 (CURRENT REVISION).
9. BAG AND TAG PART SEPARATELY.
10. COPPER PLATING SPECIFICATIONS FOR METAL 1 AND METAL 2
A. FINAL TOP METAL CU THICKNESS TO BE $.0028 \pm .0006$.
B. FINAL BOTTOM METAL Cu THICKNESS TO BE $.0028 \pm .0006$.
11. PLATING
METAL 1 AND METAL 2:
A. COPPER PLATE SHALL BE $.0028 \pm .0004$ FINISH THICKNESS. VIAS WALLS SHALL BE PLATED .0007 MIN.
B. NICKEL PLATE PER QQ-N-290, CLASS 1, GRADE G, 200u-in MIN (5um MIN)
C. GOLD PLATE PER ASTM B 488, TYPE III, CODE A, CLASS 1, 5uin MIN (.127um MIN)
D. SELECTIVE GOLD PLATE PER ASTM B 488, TYPE III, CODE A, CLASS 1, 50uin MIN (1.27 um MIN)
12. FLATNESS AT COIN AREA TO BE FLUSH -0.000 TO +0.0014 PROTRUSION.
13. COPPER COIN APERTURE TO BE EDGE PLATED. METAL 1 AND METAL 2 TO BE PLATED COMPLETELY ALONG COPPER APERTURE EDGE
14. COPPER COIN MATERIAL:
OXYGEN FREE HIGH CONDUCTIVITY COPPER UWS CDA 101, 102, OR 103, ASTM B187, ASTM B152.
15. FLATNESS AT COIN AREA TO BE FLUSH TO METAL 1 WITHIN +0.001/-0.001.
16. PLATING BETWEEN COPPER COIN AND METAL 1 & METAL 2 TO BE CONTINUOUS, (UNINTERRUPTED).
17. TOP OF COPPER COIN TO BE PLATED TO METAL 1. BOTTOM OF COIN TO BE PLATED TO METAL 2.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES [mm]	PRODUCT: TGS2355		<div>TriQuint</div> <div>500 W Renner RD. Richardson, TX 75080 Phone: 972.994.8200 www.triquint.com</div>	
	PROJECT:			
TOLERANCES X.XX = ±.01 X.XXX = ±.005 X.XXXX = ±.0010 ANGLES = 0.5°	APPROVAL AND RELEASE RECORDS MAINTAINED IN PDM		DATE	
	DESIGNER	TMONTIERTH	4/13/2015	
INTERPRET DRAWING PER ANSI/ASME Y14.5 - 2009	ENGR.	R.SANTHAKUMAR	4/13/2015	
	MFG.			
 THIRD ANGLE PROJECTION	MANAGER		SIZE	
	Q.A.		DWG. NO.	
DO NOT SCALE DRAWING	CAGE CODE	1CVM1	B	
			AD1_1127937	
			REV. A	
			SCALE NTS	
			SHEET 1 OF 3	

THIS DOCUMENT IS CONFIDENTIAL AND REPRESENTS PROPRIETARY INFORMATION, THE PROPERTY OF TRIQUINT SEMICONDUCTOR, AND SHALL NOT BE REPRODUCED IN ANY MANNER NOR USED FOR ANY PURPOSE WHATSOEVER, EXCEPT AS SPECIFIED IN WRITING BY TRIQUINT SEMICONDUCTOR

8

7

6

5

4

3

2

1

D

D

C

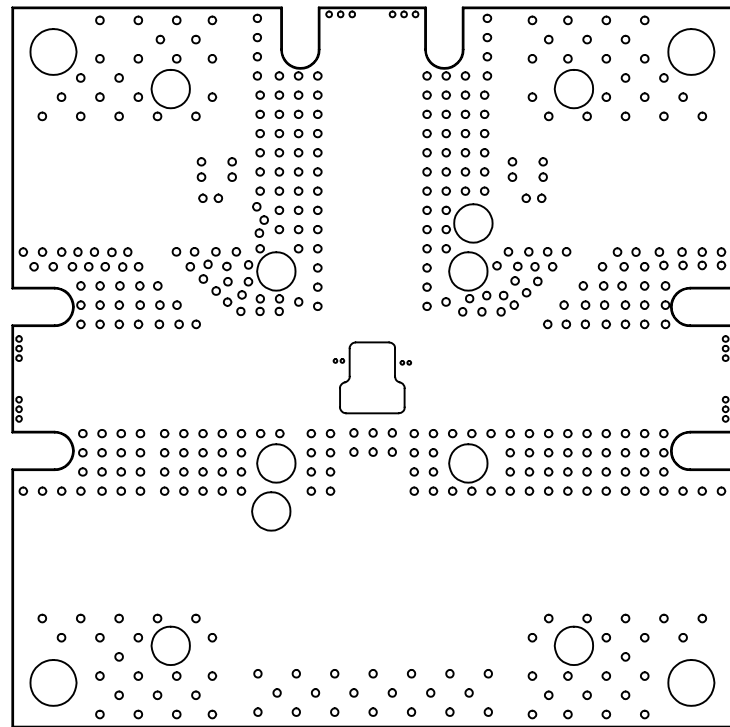
C

B

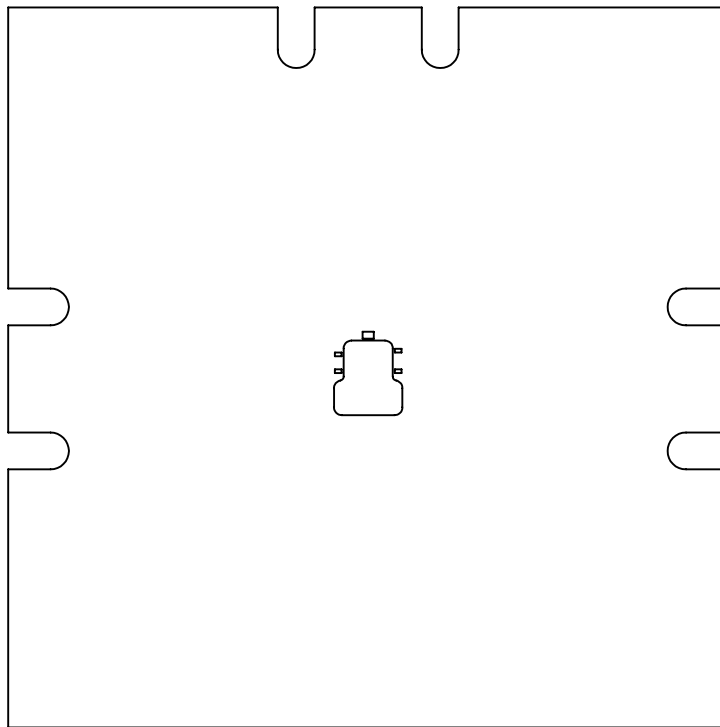
B

A

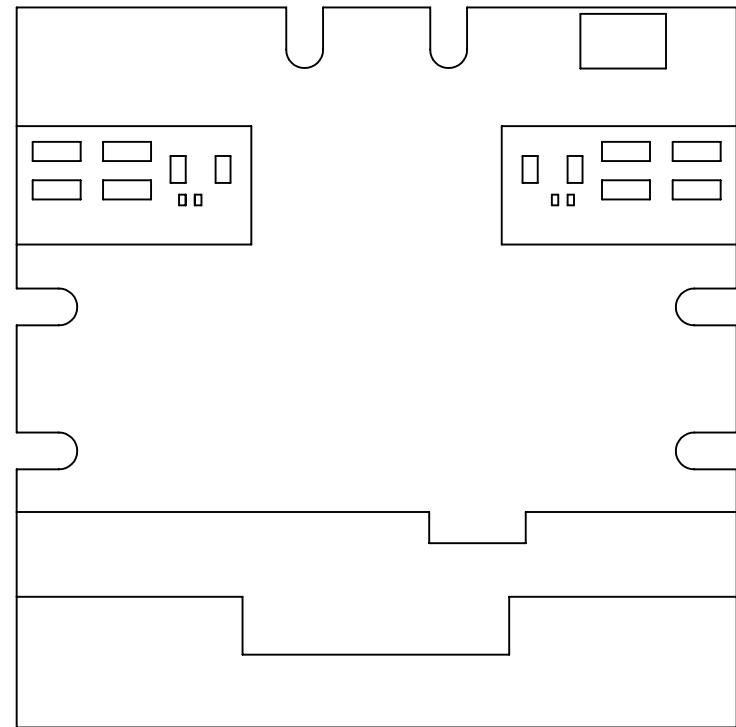
A



METAL 2 (BOTTOM)



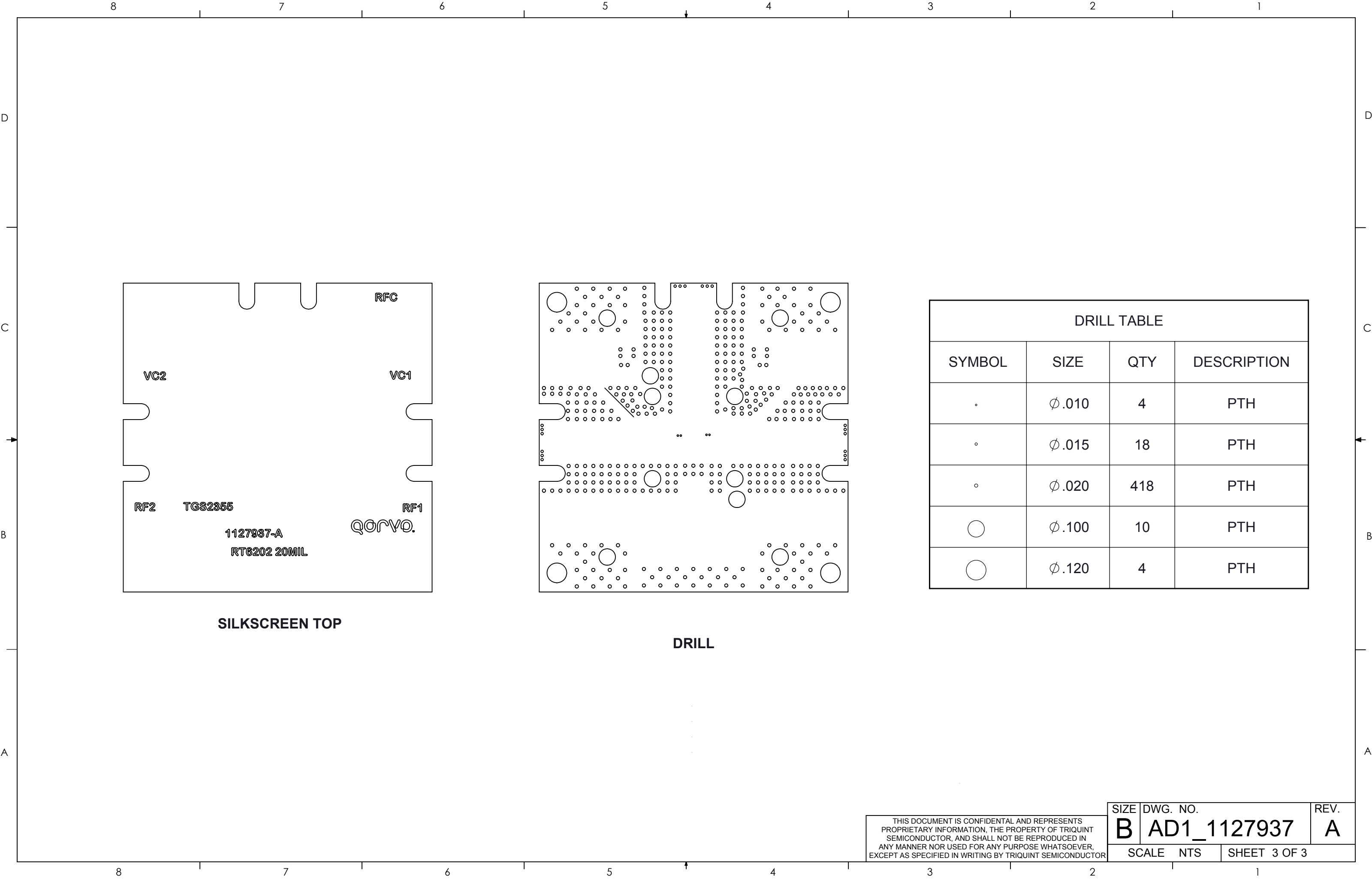
SELECT GOLD



SOLDERMASK TOP

THIS DOCUMENT IS CONFIDENTIAL AND REPRESENTS
PROPRIETARY INFORMATION, THE PROPERTY OF TRIQUINT
SEMICONDUCTOR, AND SHALL NOT BE REPRODUCED IN
ANY MANNER NOR USED FOR ANY PURPOSE WHATSOEVER,
EXCEPT AS SPECIFIED IN WRITING BY TRIQUINT SEMICONDUCTOR

SIZE	DWG. NO.	REV.
B	AD1_1127937	A
SCALE	NTS	SHEET 2 OF 3



SILKSCREEN TOP

DRILL

DRILL TABLE			
SYMBOL	SIZE	QTY	DESCRIPTION
.	Ø.010	4	PTH
°	Ø.015	18	PTH
◦	Ø.020	418	PTH
◯	Ø.100	10	PTH
◯	Ø.120	4	PTH

THIS DOCUMENT IS CONFIDENTIAL AND REPRESENTS PROPRIETARY INFORMATION, THE PROPERTY OF TRIQUINT SEMICONDUCTOR, AND SHALL NOT BE REPRODUCED IN ANY MANNER NOR USED FOR ANY PURPOSE WHATSOEVER, EXCEPT AS SPECIFIED IN WRITING BY TRIQUINT SEMICONDUCTOR

SIZE	DWG. NO.	REV.
B	AD1_1127937	A
SCALE	NTS	SHEET 3 OF 3